



T STRATEGY ALLIANCE

2467.TW

c sun志聖

5443.TW

GPM 均豪

6640.TW

GMM 均華



Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.

Business Philosophy- **ALL WIN**



G2C+

合力共創 同行致遠

Well-intentioned motives
lead careers to success

---From 『Heart』 Inamori
Kazuo



C Sun Mfg Ltd.

Investor's Meeting
2025.5.19

Stock No.
2467.TW
c sun 志聖



The Alliance Members: 1700+



R&D personnel: 560+

R&D personnel account for 32.5%



Since 1966

Since 1978

Since 1978

***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

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Bonder
Lamination
Peeling
Thermal

GPM

AOI
Metrology
Grinding
Polishing

GMM

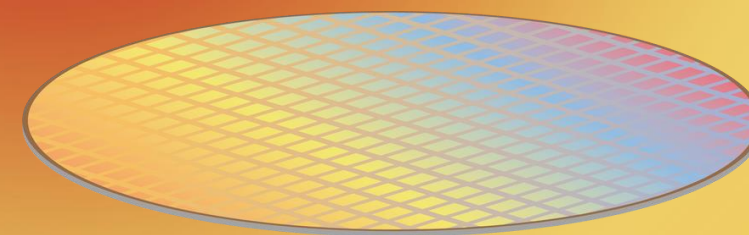
Die Attach
Chip Sorter
Auto Jig Saw

Advanced packaging

IC Substrate 、 HBM Packaging 、 2.5/3DIC



GT2C+
T STRATEGY ALLIANCE



c sun GPM

Foundry

Reclaim wafer

Four Phases of AI Development

Perceptual AI

Perceive images, sounds, and environmental information

2012 年
AlexNet



Generative AI

Content Generation
(Language 、 Image)

Chat GPT

 **Gemini**

ANTHROPIC

Deepseek

Reasoning AI

Understand Rules
Use Tools
Solve Problems

AI Agent



Physical AI

Possesses
Causal Reasoning
Physical Intuition

NVIDIA
Cosmos AI



Taiwan's West Golden Corridor: **AI Chips**

The Shining Diamond Chain of Advanced Packaging Processes

Taiwan's Market Share in
Packaging and Testing by Value

58.6 %

76.8 %

Taiwan's Market Share in
Wafer Manufacturing by Value



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Foundry 2.0

Downstream
Integration

Info
cWoS
Solc

Advanced Packaging

OSAT
Upstream
Development

MEM

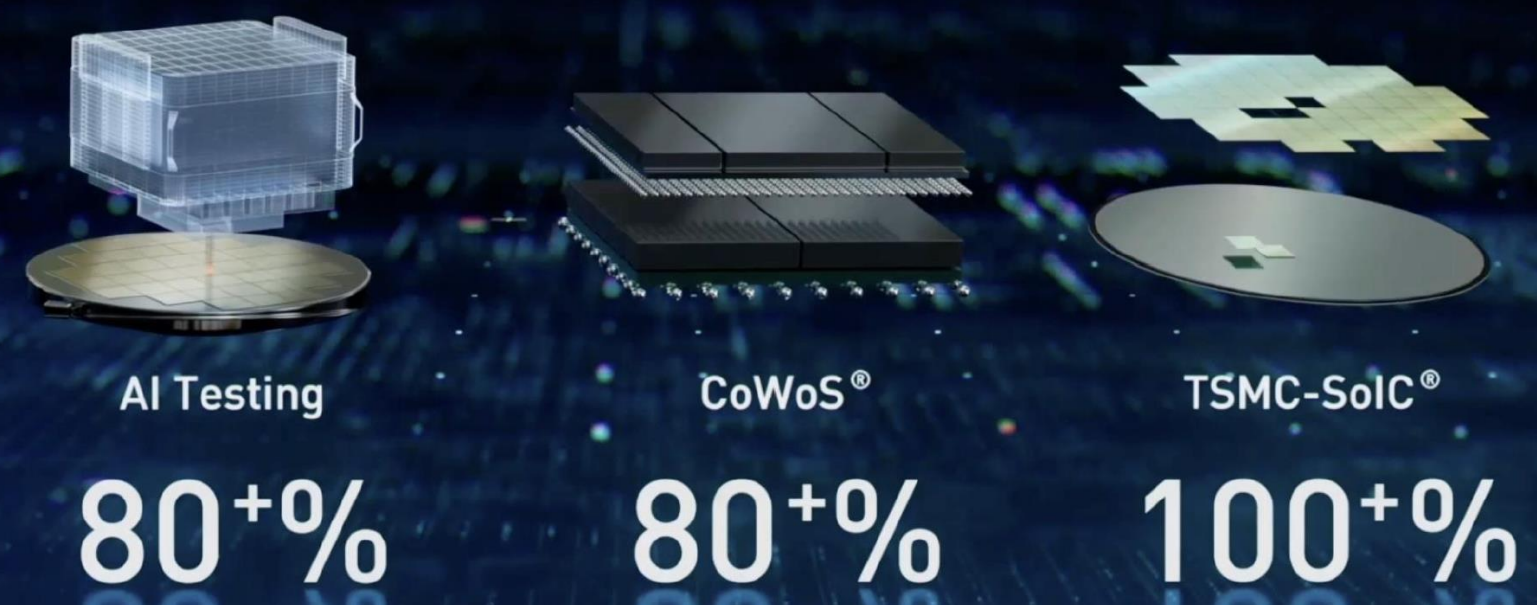
FOCOS

SiP

PLP

FC → WLCSP → 2.5D

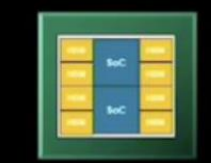
2022-2026 Expansion Capacity CAGR



TSMC-SoW™ (System-on-Wafer) Boosts AI Compute

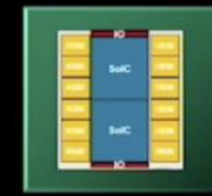
- Wafer-scale integration maximizes computing power
- SoW-X technology for wafer-scale logic and HBM integration will be ready in 2027

Compute 1X



CoWoS (SoC)
3.3-ret., 8x HBM
80x80mm substrate

3.5X



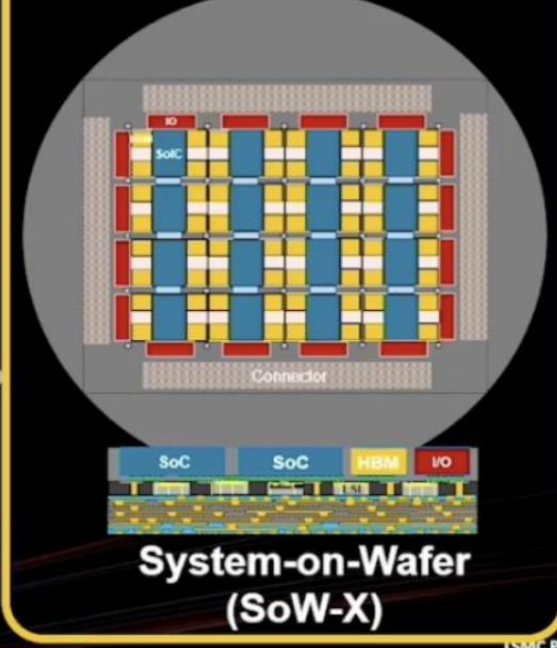
CoWoS (SolC)
5.5-ret., 12x HBM
100x100mm substrate

7X



CoWoS (SolC)
9.5-ret., 12x HBM
120x150mm substrate

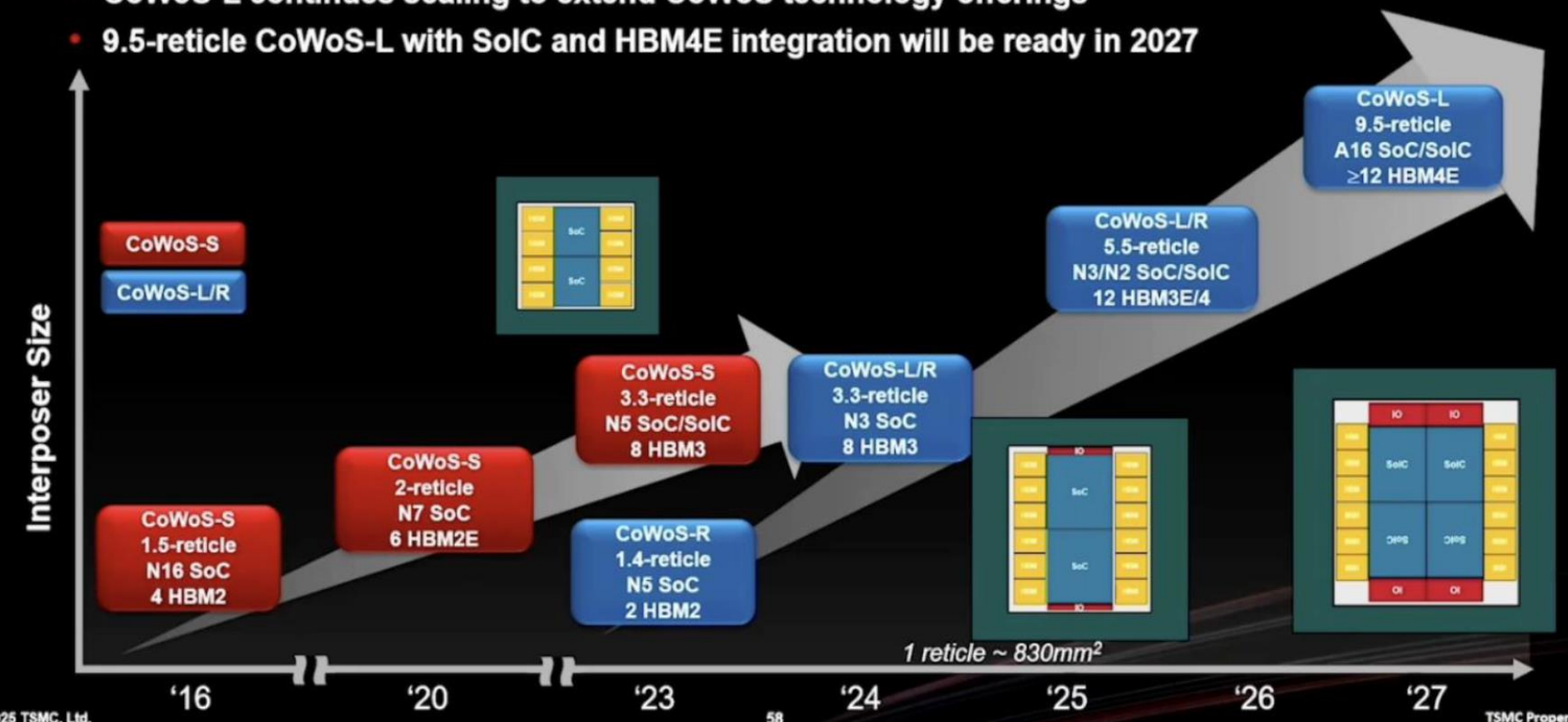
>40X



System-on-Wafer (SoW-X)

CoWoS® Enables AI Compute Scaling

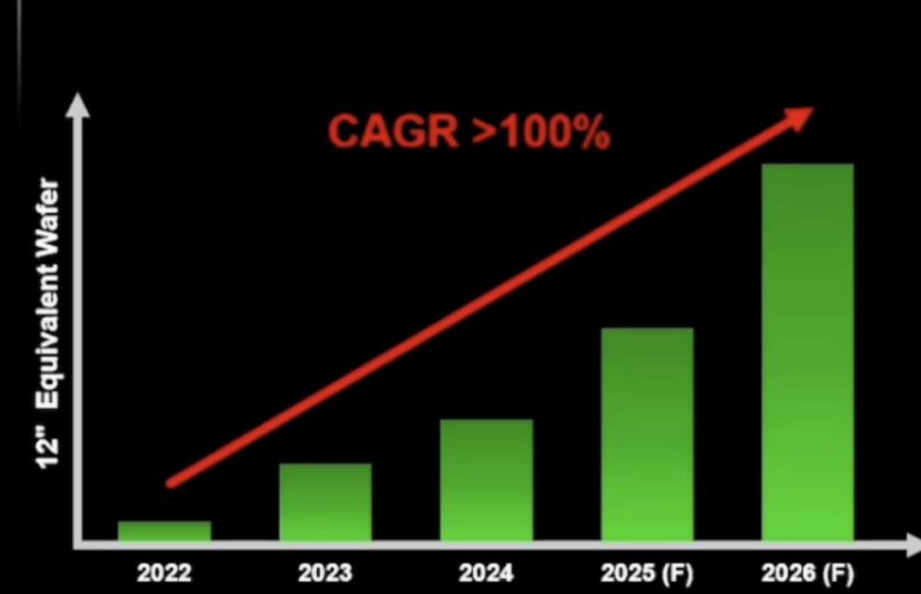
- CoWoS-S has been in production for over 10 years with interposer size up to 3.3-reticle
- CoWoS-L continues scaling to extend CoWoS technology offerings
- 9.5-reticle CoWoS-L with SolC and HBM4E integration will be ready in 2027



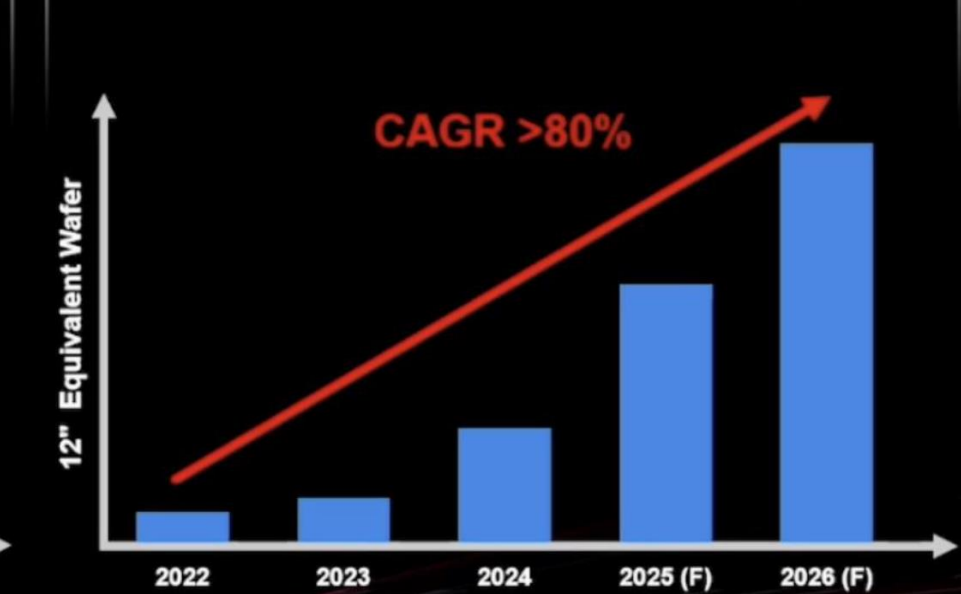
TSMC 3DFabric® Capacity Growth

- Accelerating 3DFabric™ capacity expansion to support explosive HPC/AI demand

SolC® Capacity



CoWoS® & AI Testing Capacity



Company Introduction



2023、2024
TSMC Award

Employee and Family
Shareholding >40%

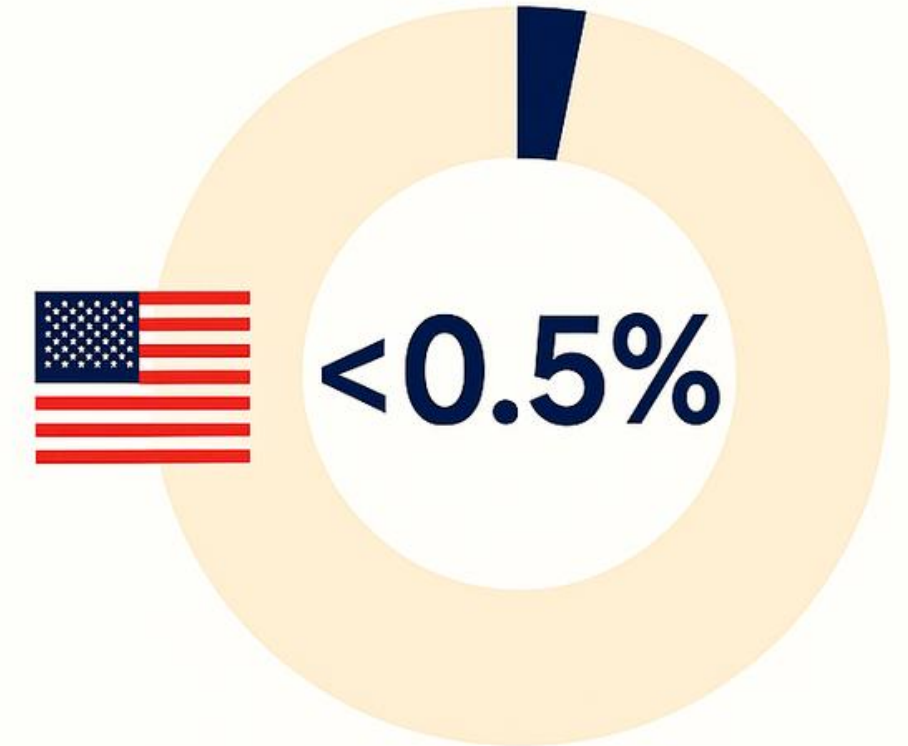


Establishment: 1966.9.28
Capital: NT\$1.56 billion
Chairman: Morrison Liang
President: Frank Liang

Shifting Trade Dynamics: Tariffs and FX Volatility



FOB TRANSACTION



Past 3 Years



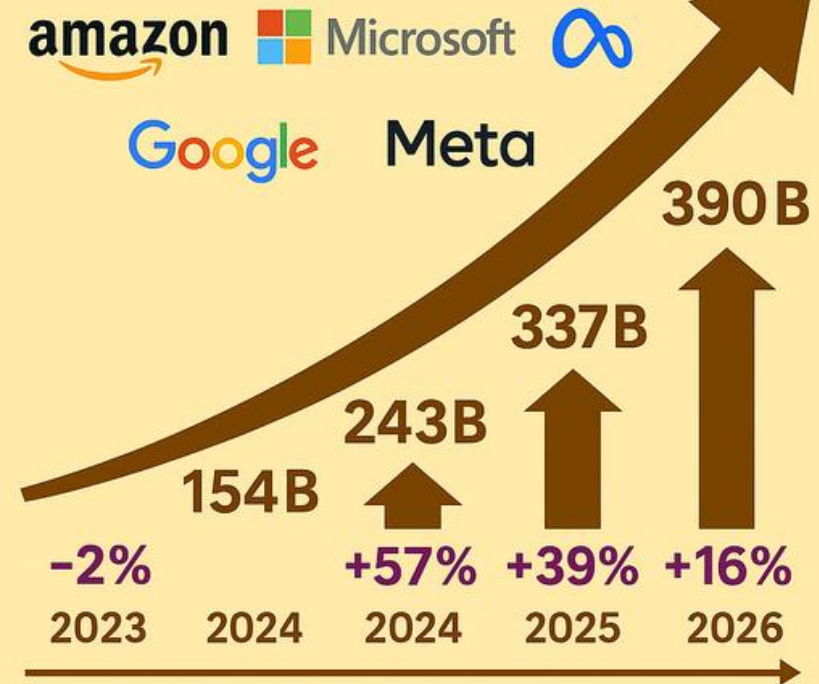
Key Customer
Transaction Currency



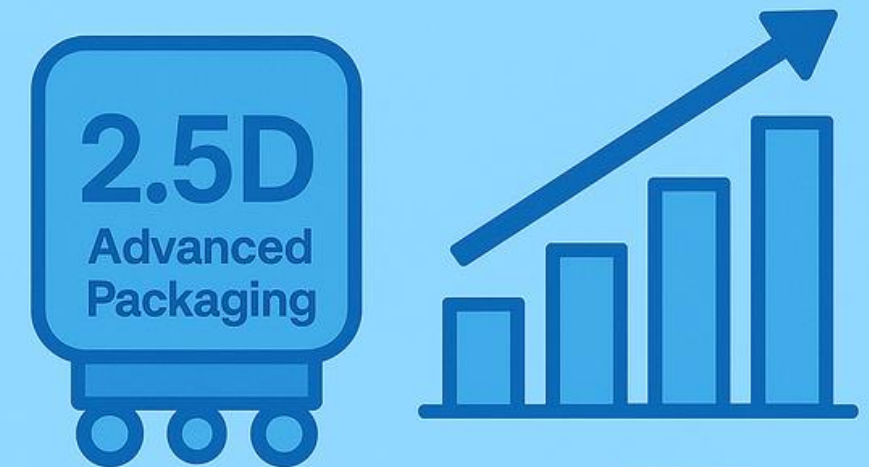
USD backlog
≈ 10% of total orders

Business goals continue and follow the technological development of leading customers

Top 4 US Hyperscalers Continue Upgrading Cloud Capex Forecasts



Demand Forecast Remains the Same



Vacuum Pressure Oven



with Key Customer



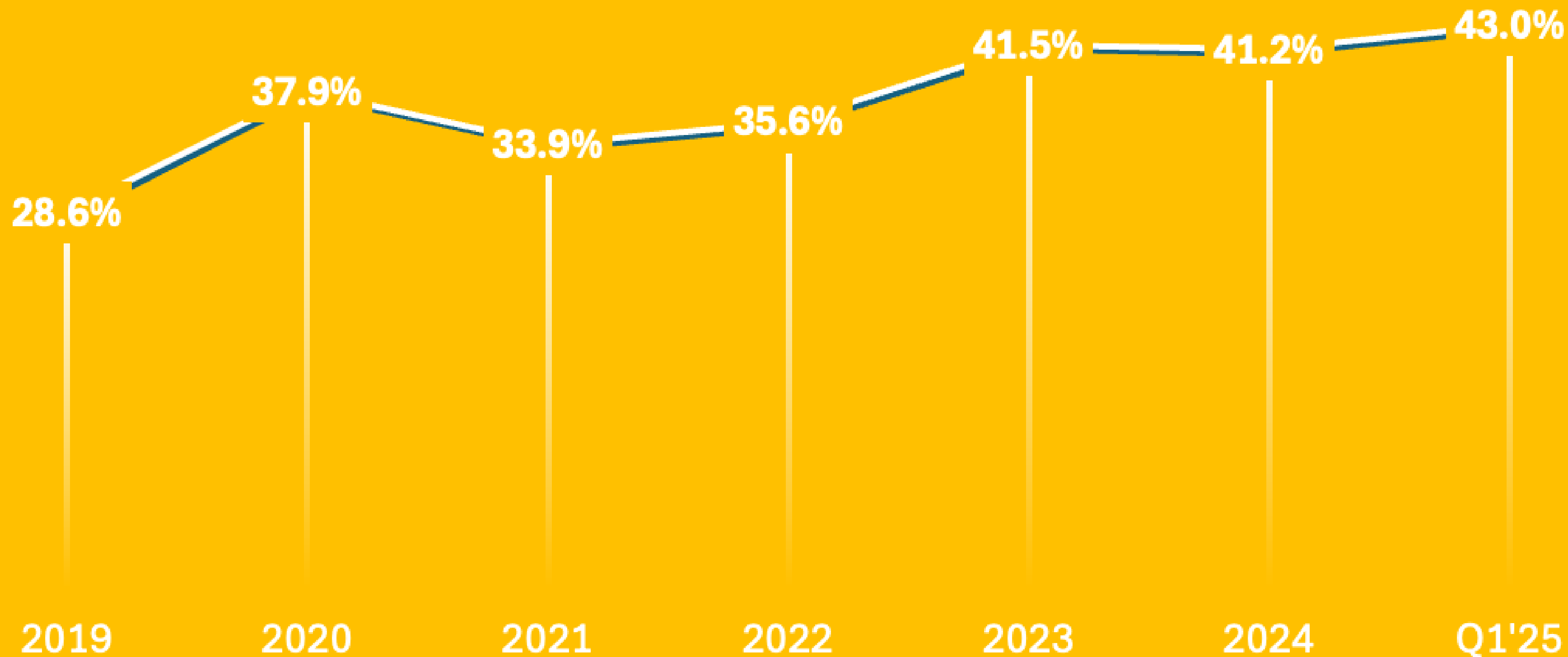
Financial Review

Selected Items from Statements of Comprehensive Income

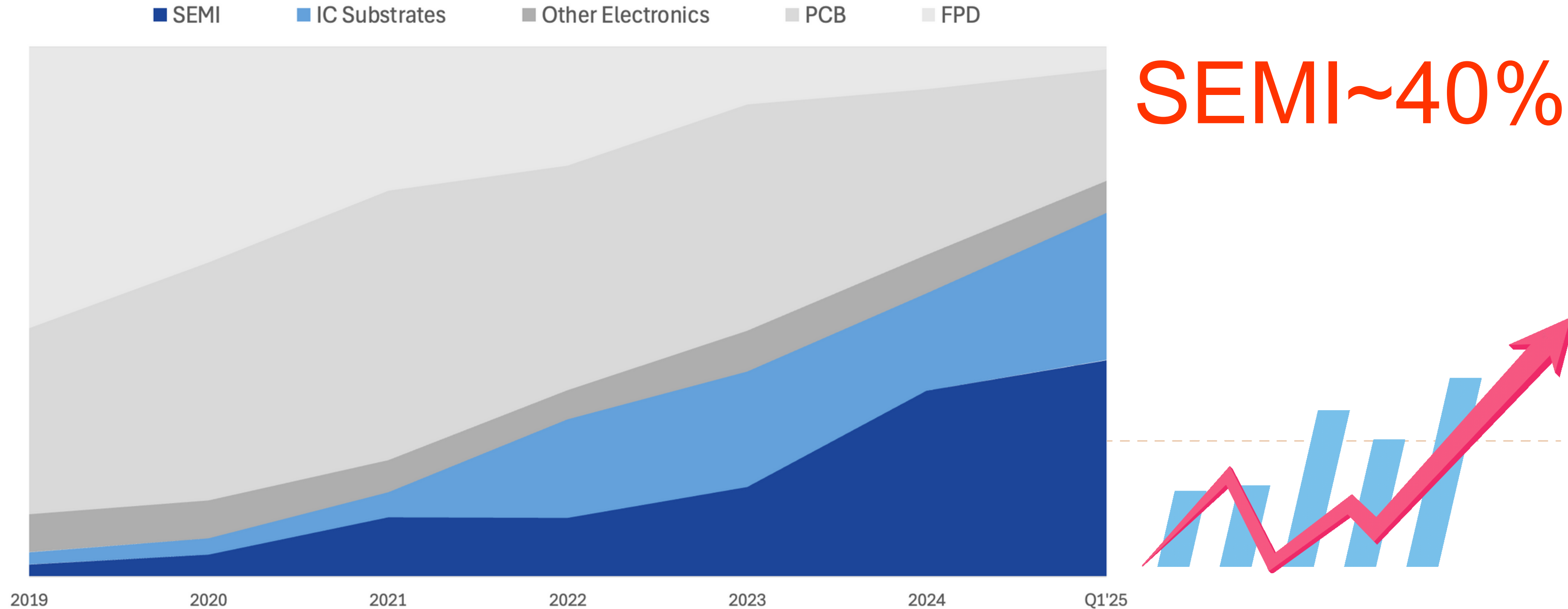
(In NT\$ millions unless otherwise noted)

	1Q25	4Q24	1Q24	QoQ	YoY
Revenue-Consolidated	1,309	1,335	1,080	-2.0%	21.2%
Gross Margin%	43.0%	41.9%	43.2%	+1.1ppts	-0.2ppts
Operating Expense	(383)	(336)	(312)	14%	23%
Operating Expense%	29.2%	25.1%	28.9%	+4.1ppts	+0.3ppts
Operating Margin%	13.8%	16.7%	14.3%	-2.9ppts	-0.5ppts
Non-Operating Items	59	77	86	-23%	-31%
Net Income Attributable to Shareholders of the Parent Company	150	195	172	-23%	-13%
Net Profit Margin%	11.5%	14.6%	15.9%	-3.1ppts	-4.4ppts
EPS (NT\$D)	1	1.3	1.15	-23%	-13%

Gross Margin Rate



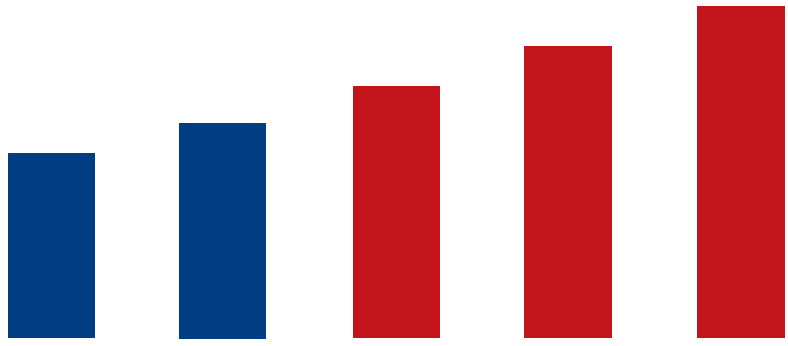
Revenue Composition





OSATs' Revenue Composition Growth

TOP 10 OSATs Are All Customers of G2C+

4  10%

%



ASE



JCET

TF 通富微電



CHIPBOND
順邦科技

c sun 志聖

Focusing

AI 聚焦

HBM

oS

LPO

Assembly

IC Substrate

CoW

SoC/SolC

CPO

Test

Mother Board

2024

>50%

The 12th Corporate Governance Evaluation

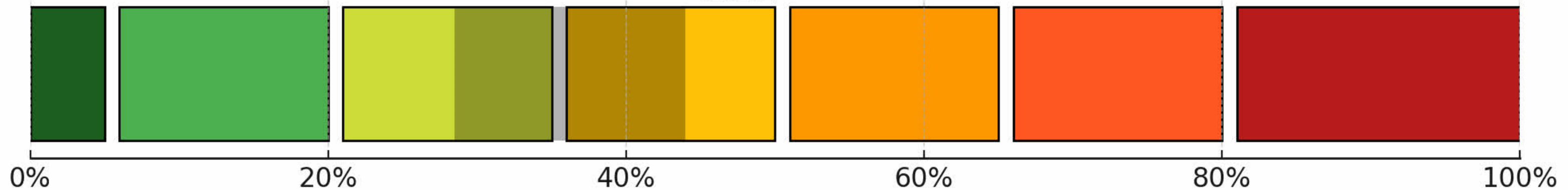


Protecting Shareholder Rights



Strengthening Board Structure

□□□□□□□□: 28%~44%



Enhancing Information Transparency



Promoting Sustainable Development

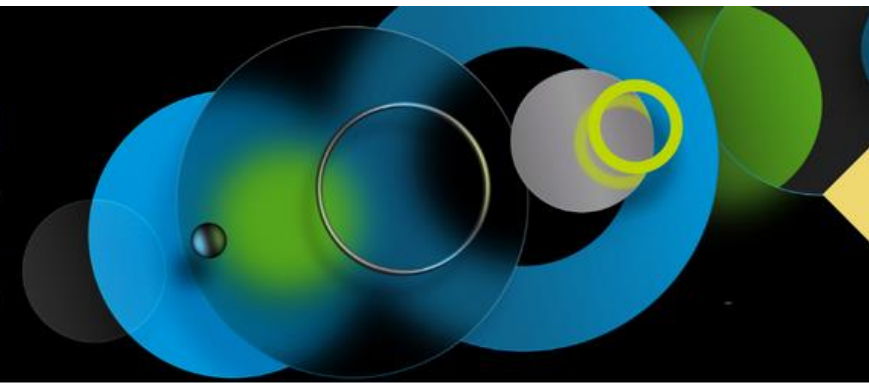


G20+



*c sun*志聖 Exhibition Preview

SEMICON[®] SOUTHEAST ASIA 30 YEARS Special Edition
MAY 20-22, 2025 10:00~17:00 SGT
SANDS EXPO & CONVENTION CENTRE
SINGAPORE



BASEMENT 2
B1524

We sincerely invite you to visit our exhibition booth for inquiries.
Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.



The 2025 IEEE 75th
Electronic Components
and Technology Conference

May 27 – 30, 2025

Gaylord Texan Resort & Convention Center
Dallas, Texas, USA

Booth No.
111

We sincerely invite you to visit our exhibition booth for inquiries.
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Invitation

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C sun

A **G2C+** Alliance Company

Thank you for your attention
